

### **AMENDMENTS TO THE SPECIFICATION**

Please replace the paragraph [0015] of the application as filed with the following rewritten paragraph:

**[0015]** U.S. Patent No. 6,121,689 discloses a semiconductor flip-chip package, which includes a polymerizable fluxing agent. FIGS. 1 and 2 herein depict flip-chip structures as set forth in the '689 patent. As is apparent, the flip-chip structure of FIG. 1 includes a chip 10 having solder bumps 14 pre-assembled thereon on contact pads 24 on bottom surface 16 of chip 10 for electrical connection with solder pads 12 of a substrate 20 through the use of an encapsulant 22. In further embodiments, a fluxing adhesive may be used to adhere the chip 10 to the substrate 20. Moreover, as shown in FIG. 2, the structure may also include a multi-layer encapsulant material 36, including attachment and stress distribution layers 38 and 40, and thermoplastic reworkability layer 42. This thermoplastic reworkability layer is generally a meltable polymer such as a polyimide-siloxane copolymer. As shown in FIG. 2, flux adhesive 34 may be provided between the chip 10 and the substrate 20 for attachment of the chip 10 to the substrate 20. Adhesion and mechanical strength of the underfill sealant may be compromised due to the incorporation of the fluxing agent and the adhesive in a single composition. Also, when an integrated circuit chip includes an encapsulant having a fluxing adhesive incorporated therein, the fluxing adhesive may adversely affect the encapsulant material, thereby reducing the shelf stability or pot-life. Also, the use of a thermoplastic material as the reworkability layer provides the assembly with limited rework properties.